PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

 SUBMISSION TYPE:
 NEW ASSIGNMENT

 NATURE OF CONVEYANCE:
 ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Gyu-su LEE	12/04/2007

RECEIVING PARTY DATA

Name:	Samsung Electronics Co., Ltd.	
Street Address:	416, Maetan-dong, Yeongtong-gu	
City:	Suwon-si, Gyeonggi-do	
State/Country:	REPUBLIC OF KOREA	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11952574

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: SWO-0106

NAME OF SUBMITTER: James J. Merrick

Total Attachments: 2

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PATENT REEL: 020213 FRAME: 0963

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ASSIGNMENT

WHEREAS We, **LEE**, **Gyu-su** of Cheongmyeong Maeul 4-danji Apt. #426-1503, Yeongtong-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Korea (hereinafter referred to as ("ASSIGNOR") have invented certain new and useful improvements in:

FILM-CHIP COMPLEX, METHOD OF MANUFACTURING FILM-CHIP COMPLEX AND DISPLAY DEVICE HAVING THE SAME

which claims priority to Korean Application No 10-2007-0030441 filed March 28, 2007 for which We have filed the Patent Application No. ______ for Letters Patent of the United States; AND WHEREAS, SAMSUNG ELECTRONICS CO., LTD. (hereinafter ref erred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Countr y of Korea, having a place of business at 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gye onggi-do, Korea, is desirous of acquiring an interest in the United States and all foreign coun tries, in and to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

PATENT REEL: 020213 FRAME: 0964

The undersigned declare that all statements made herein of their own knowledge are tr ue and that all statements made on information and belief are be eved to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the

United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

LEE, Gya-su L.S.